Material declaration form

General Information

IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field*	

Supplier Information

Company name*	STMicroelectronics	Response Date*	2024-06-24
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	gregorio duro	Representative title	ADGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by
Gregorio Duro
Date: 2024.06.24
09:26:25 CEST

Material declaration form

ACTIVE: 6/24/2024

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
L9965T-TR	AA5V*UR1TBAP	A	9991	2024-06-24
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	180.00	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM01047099	
Package designator	Package size	Number of instances	Shape	
Not Applicable	7.00x7.00x1.40	32	0	
Comment	LQFP 32 7x7x1.4 1			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**True**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	False
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	False
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	False
Exemption Id.	**Description**

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	**Response**
1 - Product(s) meets EU ELV requirements without any exemptions	**True**
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	False
Exemption Id.	**Description**

QueryList : California Prop65 list, dated 17th Nov 2023			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			False
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			**True**
Substance	**amount in product (mg)**	**Application**	**ppm in product**
Nickel	1.759	die - leadframe	9772

QueryList : REACH-23rd January 2024				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				True
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				True
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material

QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	**Tin, Tungsten,**

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	False

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	False

Stockholm Convention Persistent Organic Pollutants	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	True

QueryList : EUSRR Directive	Response
Product contains hazardous materials listed in EUSRR Annex II	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**AA5V*UR1TBAP**					
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	M-011 Other inorganic materials	4.091	mg	supplier	die	Silicon(Si)	7440-21-3		3.706	mg	905891	20589
				supplier	metallisation	Copper(Cu)	7440-50-8		0.253	mg	61843	1406
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.028	mg	6844	156
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.009	mg	2200	50
				supplier	metallisation	Tungsten(W)	7440-33-7		0.012	mg	2933	67
				supplier	passivation	Silicon oxide	7631-86-9		0.040	mg	9778	222
				supplier	polymer coating	polyimide	proprietary		0.043	mg	10511	239
Leadframe	M-004 Copper and its alloys	58.841	mg	supplier	alloy	Copper(Cu)	7440-50-8		55.516	mg	943492	308422
				supplier	alloy	Nickel(Ni)	7440-02-0		1.731	mg	29418	9617
				supplier	alloy	Silicium (Si)	7440-21-3		0.375	mg	6373	2083
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.087	mg	1479	483
				supplier	metallization	Silver (Ag)	7440-22-4		1.132	mg	19238	6289
Die attach	M-011 Other inorganic materials	0.512	mg	supplier	glue	Silver(Ag)	7440-22-4		0.384	mg	750000	2133
				supplier	glue	Resin	proprietary		0.128	mg	250000	711
Bonding wires	M-004 Copper and its alloys	0.243	mg	supplier	wire	Copper(Cu)	7440-50-8		0.239	mg	983539	1328
				supplier	wire	Palladium(Pd)	7440-05-3		0.004	mg	16461	22
Encapsulation	M-011 Other inorganic materials	115.612	mg	supplier	mold compound	Silver(Ag)	7440-22-4		101.075	mg	874260	561528
				supplier	mold compound	Isobornyl Methacrylate	7534-94-3		9.996	mg	86462	55533
				supplier	mold compound	Bismaleimide resin	35325-39-4		3.997	mg	34573	22206
				supplier	mold compound	Polymer	proprietary		0.544	mg	4705	3022
Connections coating	Solder	0.701	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.701	mg	1000000	3894